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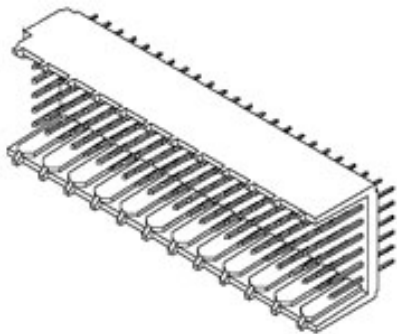
Part Number: 0739425200
Status: Active
Overview: HDM Backplane Connector System
Description: HDM Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:
[3D Model](#) [Packaging Specification PK-70873-0818 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73942
Application	Backplane
Comments	Solder Tail, Solder Tail
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754842341

Physical	
Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	6.273/g
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.00mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole

Electrical	
Current - Maximum per Contact	1.0A



Series image - Reference only

EU ELV Not Relevant	
EU RoHS Compliant REACH SVHC Not Contained Per - ED/71/2019 (16 July 2019) Halogen-Free Status Low-Halogen For more information, please visit Contact US	China RoHS China ROHS ELV RoHS Phthalates
	Green Image Not Relevant Not Contained

Search Parts in this Series
73942 Series

Mates With
73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling FAQ <i>Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.</i>	
Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Insertion	622005703
Head for 144 Circuits	

Data Rate	1.0 Gbps
Voltage - Maximum	250V AC
Solder Process Data	
Duration at Max. Process Temperature (seconds)	040
Lead-freeProcess Capability	SMC&WAVE
Max. Cycles at Max. Process Temperature	003
Process Temperature max. C	260
Material Info	
Reference - Drawing Numbers	
Packaging Specification	PK-70873-0818
Sales Drawing	SD-73942-001

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